

BOARD CHARACTERISTICS

Copper Layer Count: 2
Board overall dimensions: 30.0000 mm x 46.5000 mm
Min track/spacing: 0.1270 mm / 0.1270 mm
Copper Finish: None
Castellated pads: No
Edge card connectors: No

Board Thickness: 1.6000 mm
Min hole diameter: 0.3000 mm
Impedance Control: No
Plated Board Edge: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.465 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0